

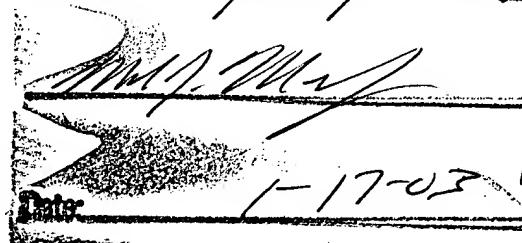


Attorney Docket SEL 189

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of )  
Takayama et al. )  
Serial No.: 09/598,736 )  
Filed: June 21, 2000 )  
For: Wiring Material, Semiconductor Device )  
Provided With A Wiring Using The Wiring )  
Material And Method Of Manufacturing Thereof )  
Art Unit: 2811 )  
Examiner: H. Vu )

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Commissioner for Patents  
Washington, D.C. 20231

January 17, 2003

**AMENDMENT B**

Sir:

In response to the Final Rejection of July 18, 2002, a RCE and three month extension of time  
being submitted herewith, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please amend the claims as follows:

*Sub C17* 1. (Twice Amended) A semiconductor device comprising:

a wiring formed over a substrate, the wiring comprising a tungsten nitride film and a  
tungsten film formed thereon,

wherein the wiring include at least one inert element, and 90% or more of the inert  
element is argon, and

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